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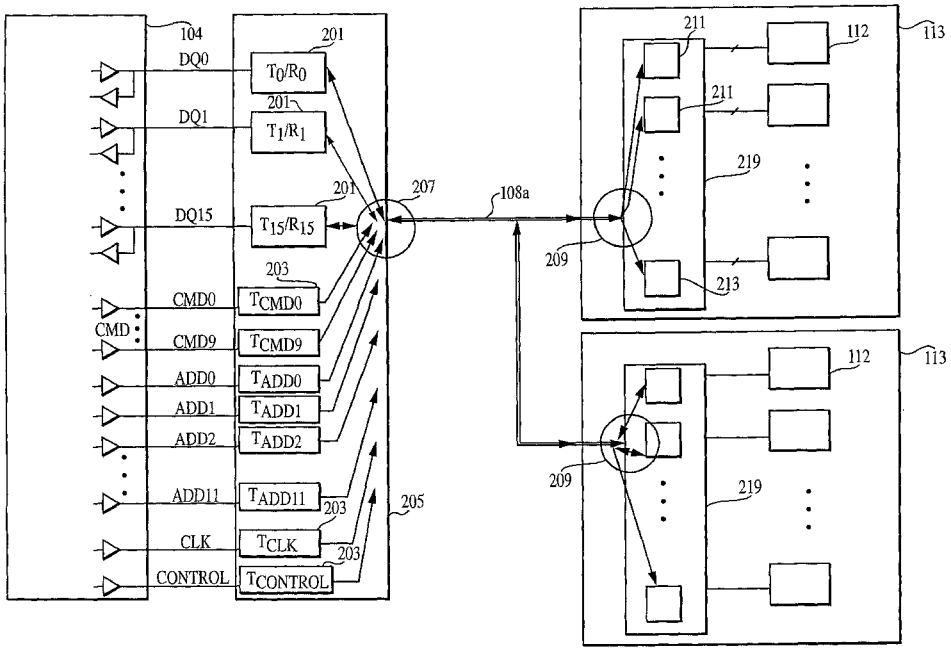
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(54) Title: AN OPTICAL INTERCONNECT IN HIGH-SPEED MEMORY SYSTEMS



(57) Abstract: An optical link for achieving electrical isolation between a controller and a memory device is disclosed. The optical link increases the noise immunity of electrical interconnections, and allows the memory device to be placed a greater distance from the processor than is conventional without power-consuming I/O buffers.

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